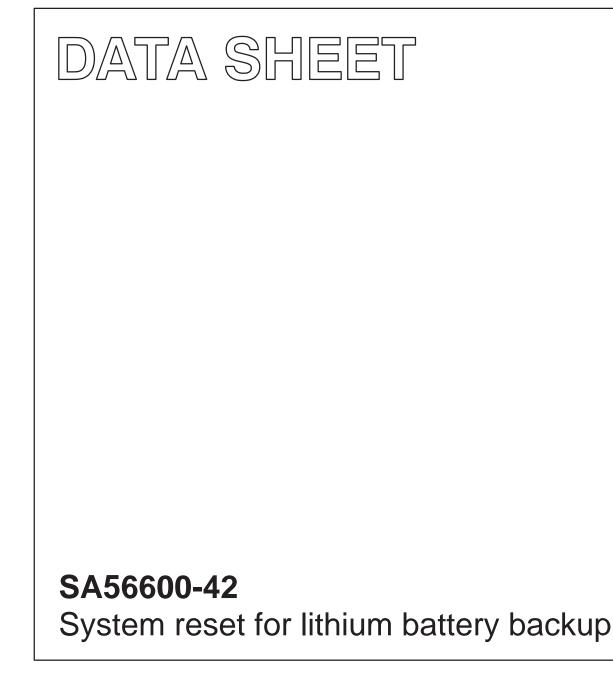
INTEGRATED CIRCUITS



Product data Supersedes data of 2001 Apr 24 File under Integrated Circuits, Standard Analog 2001 Jun 19





SA56600-42

GENERAL DESCRIPTION

The SA56600-42 is designed to protect SRAM data in computer systems during periods of sagging power supply voltages and power outages. When the power supply voltage drops to typically 4.2 V, the CS output goes to a logic LOW state pulling CE to a LOW state, disabling the SRAM device. In addition, a reset logic LOW is asserted for system use. If the supply voltage drops further, to 3.3 V typically or lower, the SA56600-42 switches the system's operation from the main power supply source to the Lithium back-up battery. As the main supply is restored and the voltage rises to 3.3 V or higher, the SRAM support voltage transfers from the Lithium back-up battery to the main supply. When the main supply voltage rises to greater than typically 4.2 V, the CS output goes to a logic HIGH state for SRAM CE control. Reset assertion is released and normal operation is resumed. This sequence ensures reliable preservation of SRAM data during periods of supply deficiency and interruptions.

The SA56600-42 is offered in the SO8 surface mount package.

FEATURES

- Supply switching at 4.2 V_{DC} threshold (falling supply)
- RESET output
- Both CS and CS outputs available for SRAM control
- During battery back-up operation:
 - Low supply current (0.3 µA typical)
 - Low input/output voltage drop (0.3 V typical at 100 μA)
 - Low reverse current leakage (0.1 µA max.)
- During normal operation:
 - Low input/output voltage drop (0.2 V typical at 50 mA)
 - 4.8 V typical output voltage at 50 mA with V_{CC} = 5.0 V
 - Restoration of main supply operation at 3.3 V

APPLICATIONS

- Memory cards (SRAM)
- PCs, word processors
- FAX machines, photocopiers, office equipment
- Sequence controllers
- Video games and other equipment with SRAM

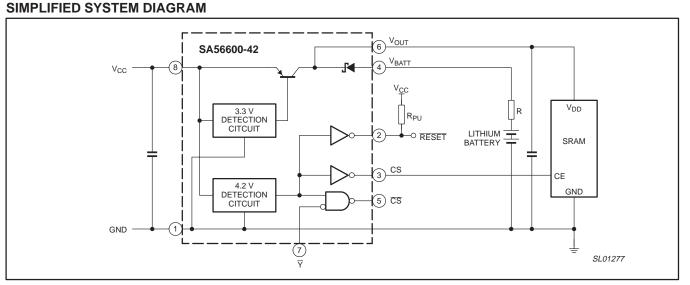


Figure 1. Simplified system diagram.

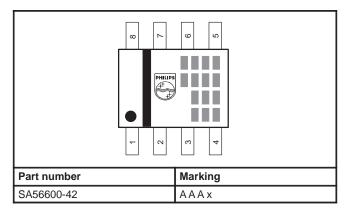
ORDERING INFORMATION

			TEMPERATURE
I TPE NOWBER	NAME	DESCRIPTION	RANGE
SA56600-42D	42D SO8 plastic small outline package; 8 leads; body width 3.9 mm		–40 to +85 °C

SA56600-42

Part number marking

The package is marked with a four letter code in the first line to the right of the logo. The first three letters designate the product. The fourth letter, represented by 'x', is a date tracking code. The remaining two or three lines of characters are internal manufacturing codes.



PIN DESCRIPTION

DESCRIPTION PIN SYMBOL GND 1 Circuit ground for the device. 2 RESET Asserted open collector output LOW whenever the V_{CC} input source voltage falls below V_S (4.2 V typical). The open collector topology requires an external pull-up resistor. CS 3 Chip select HIGH output signal, asserted whenever the V_{CC} input source voltage is above V_S (4.2 V typical). Can be used as a chip enable HIGH (CE) signal for system SRAM. 4 V_{BATT} Positive polarity connection for lithium back-up battery. Asserted chip select LOW output signal whenever the V_{CC} input source voltage is above V_S (4.2 V typical) and \overline{Y} is grounded. Can be used as a chip enable LOW (CE) signal for system SRAM. 5 CS 6 Vout Primary power with lithium battery back-up power for the protected system. Switch over to lithium battery back-up operation occurs when V_{CC} falls below V_S. Ŧ 7 Open Emitter input to microcontroller used to enable CS output (microcontroller controls CS function). 8 V_{CC} Primary input power source for device.

MAXIMUM RATINGS

SYMBOL	PARAMETER	RATING	UNIT
V _{CC(max)}	Power supply voltage	-0.3 to +7.0	V
V _{CC(op)}	Operating voltage	-0.3 to +7.0	V
I _O (V _{CC})	Output current	80	mA
I _O (V _{BATT})	Output current	200	μΑ
T _{oper}	Operating temperature	-40 to +85	°C
T _{stg}	Storage temperature	-40 to +125	°C
Р	Power dissipation	ver dissipation 250	

PIN CONFIGURATION

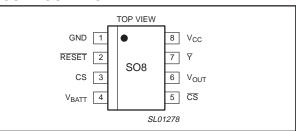


Figure 2. Pin configuration.

ELECTRICAL CHARACTERISTICS

Characteristics measured with V_{CC} = 5.0 V, and T_{amb} = 25 °C, unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CC}	Supply current $V_{CC} = 5.0 \text{ V}; \text{ V}_{BATT} = 3.0 \text{ V}; \text{ I}_{O} = 0 \text{ r}$		-	1.4	2.2	mA
V _{SAT1}	I/O voltage difference 1	$V_{CC} = 5.0 \text{ V}; \text{ V}_{BATT} = 3.0 \text{ V}; \text{ I}_{O} = 1.0 \text{ mA}$	-	0.03	0.05	V
V _{O1}	Output voltage 1	$V_{CC} = 5.0 \text{ V}; \text{ V}_{BATT} = 3.0 \text{ V}; \text{ I}_{O} = 1.0 \text{ mA}$	4.95	4.97	-	V
V _{O2}	Output voltage 2	V _{CC} = 5.0 V; V _{BATT} = 3.0 V; I _O = 15 mA	4.75	4.90	-	V
V _S	Detection threshold	V _{CC} falling	4.00	4.20	4.40	V
ΔV_S	Detection hysteresis	$\Delta V_{S} = V_{SH}$ (rising V_{CC}) – V_{SL} (falling V_{CC})	-	100	-	mA
V _{RSL}	Reset output LOW	$V_{CC} = 3.7 V$	-	0.2	0.4	V
I _{RSH}	Reset leakage current HIGH	$V_{CC} = 5.0 \text{ V}; \text{ V}_{RS} = 7.0 \text{ V}$	-	±0.01	±0.1	μΑ
V _{OPL}	Reset assertion (minimum operating voltage)	$V_{RSL} \le 0.4 \text{ V}; V_{CC} \text{ falling}; R_{PU} = 10 \text{ k}\Omega$	-	0.8	1.2	V
V _{CSL}	CS output voltage LOW	V_{CC} = 3.7 V; V_{BATT} = 3.0 V; I_{CS} = 1.0 μ A	-	-	0.1	V
V _{CSH}	CS output voltage HIGH	$V_{CC} = 5.0 \text{ V}; \text{ V}_{BATT} = 3.0 \text{ V}; \text{ I}_{CS} = -1.0 \mu\text{A}$	4.90	-	-	V
V _{CSL}	CS output voltage LOW	V_{CC} = 5.0 V; V_{BATT} = 3.0 V; I_{CS} = 1.0 μ A	-	-	0.2	V
V _{CSH}	CS output voltage HIGH	$V_{CC} = 3.7 \text{ V}; \text{ V}_{BATT} = 3.0 \text{ V}; \text{ I}_{CS} = -1.0 \mu\text{A}$	V _O – 0.1	-	-	V
$\Delta V_{S} / \Delta T$	Detection voltage temperature characteristic	$-40 \le T_{amb} \le +85$	-	-	±0.05	%/°C
V _{BT}	Battery back-up threshold	V _{CC} falling	3.15	3.30	3.45	V
V _{BT(HYS)}	Battery back-up hysteresis	$V_{BT(HYS)} = V_{BTH} (V_{CC} rising) - V_{BTL} (V_{CC} falling)$	-	100	1.0	mV
V _{BT} /∆T	Switching voltage temperature characteristic	$-40 \le T_{amb} \le +85$	-	-	±0.05	%/°C
۱L	Loss current	V_{CC} = 0 V; V_{BATT} = 3.0 V; I_O = 0 μ A	-	0.3	0.5	μΑ
V _{SAT2}	I/O voltage difference 2	$V_{CC} = 0 \text{ V}; \text{ V}_{BATT} = 3.0 \text{ V}; \text{ I}_{O} = 1.0 \mu\text{A}$	-	0.2	0.3	V
V _{O3}	Output voltage 3	V_{CC} = 0 V; V_{BATT} = 3.0 V; I_{O} = 1.0 μA	2.7	2.8	-	V
V _{O4}	Output voltage 4	$V_{CC} = 0 \text{ V}; \text{ V}_{BATT} = 3.0 \text{ V}; \text{ I}_{CS} = 100 \mu\text{A}$	2.6	2.7	-	V
V _{REF}	Reference voltage (typical)		-	1.25	-	V
I _{BL}	V _{BATT} leakage current	$V_{CC} = 5.0 \text{ V}; \text{ V}_{BATT} = 0 \text{ V}$	-	-	0.1	μΑ
I _{YLO}	Y current	$V_{CC} = 5.0 \text{ V}; \text{ V}_{BATT} = 3.0 \text{ V}; \text{ V}_{Y}^{-} = 0 \text{ V}$	-	150	400	μΑ
t _{PLH}	Y propagation delay time (Note 1)	$V\overline{Y}$ = logic LOW to logic HIGH	-	8.0	20	ns
t _{PHL}	Y propagation delay time (Note 1)	$V\overline{Y}$ = logic HIGH to logic LOW	-	8.0	20	ns

NOTE:

1. \overline{Y} input rise and fall time less than 6.0 ns. 15 pF capacitance load on \overline{CS} (Pin 5 to GND).

SA56600-42

SA56600-42

TYPICAL PERFORMANCE CURVES

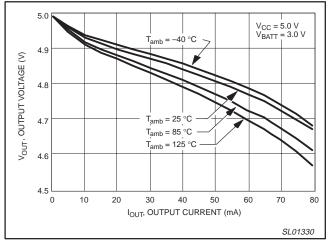


Figure 3. Output voltage versus output current.

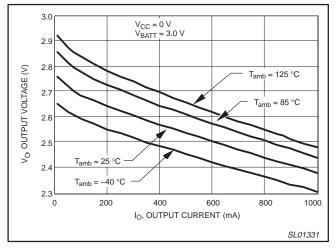


Figure 5. Output voltage versus current.

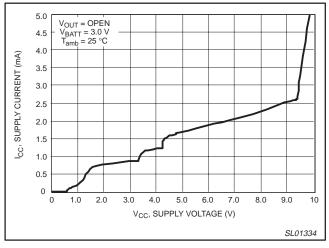


Figure 7. Supply current versus supply voltage.

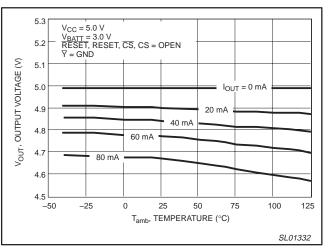


Figure 4. Output voltage versus temperature.

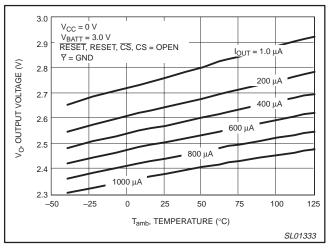


Figure 6. Output voltage versus temperature.

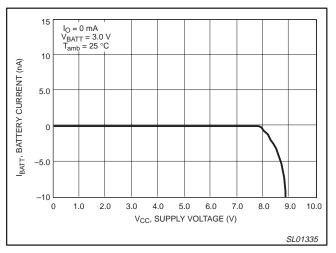


Figure 8. Battery current versus supply voltage.

SA56600-42

Product data

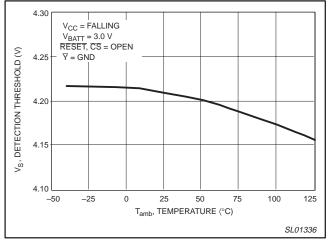


Figure 9. Detection threshold versus temperature.

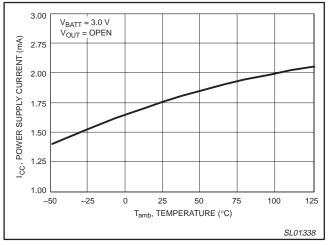


Figure 11. Power supply current versus temperature.

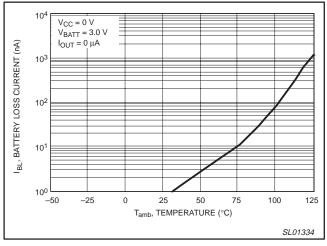


Figure 13. Battery loss current versus temperature.

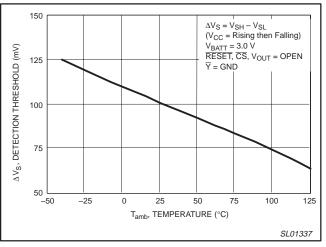


Figure 10. Detection hysteresis versus temperature.

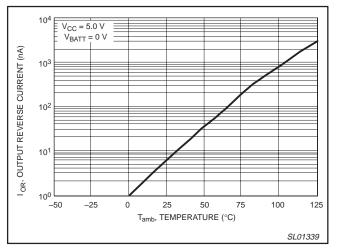


Figure 12. Output reverse current versus temperature.

SA56600-42

TECHNICAL DESCRIPTION

The SA56600-42 provides battery back-up functions to protect SRAM data in computer memory systems. In addition, it provides RESET, Chip Select HIGH (CS), and Chip Select LOW (CS) outputs. The device incorporates a 3.3 V detection circuit, 4.2 V detection circuit, PNP switching transistor, and Schottky diode for low drop lithium battery connection to the output.

During power-up, RESET is actively asserted (LOW logic state) at V_{CC} voltages as low as 0.8 V and does not output a release (HIGH logic state) until V_{CC} attains 4.2 V plus hysteresis. CS, in a similar manner, only transitions to a HIGH logic state when V_{CC} attains 4.2 V plus hysteresis. This ensures adequate voltage being present at the output of the SA56600 for proper operation of the associated computer system.

If the V_{CC} voltage falls below 4.2 V, CS and RESET both go to a LOW logic state. During this time, with CS in a LOW logic state, no data ca be read from, or written to, the SRAM device. If the primary voltage (V_{CC}) continues to fall to 3.3 V and below, the PNP switching transistor disconnects the primary input source power (V_{CC}) from the output and the Schottky diode automatically couples the lithium battery power to the output of the SA56600 to supply sustaining power to the SRAM memory.

The SA56600 provides complementary CS and $\overline{\text{CS}}$ outputs. The outputs differ in ways other than being simple complements of each other. The logic state of CS is strictly a function of V_{CC} voltage. When V_{CC} is above 4.2 V plus hysteresis, CS is in a HIGH logic state. When V_{CC} is below 4.2 V, CS is in a LOW logic state.

 \overline{CS} goes to a LOW logic state only when V_{CC} is above 4.2 V plus hysteresis, and \overline{Y} is simultaneously at a LOW logic state. If \overline{Y} is not a LOW logic state (is open or at a HIGH logic state) \overline{CS} will be at a HIGH logic state. Essentially, \overline{Y} functions as a control switch for \overline{CS} and is normally used as an input gating signal from the computer's microprocessor.

Caution should be exercised in the application to keep the voltage on \overline{Y} to less than 5.0 V when the V_{CC} voltage is less than 4.2 V to avoid breaking down the Emitter-Base junction of the internal NPN transistor associated with \overline{Y} . Breakdown of the junction may produce excessive current flow causing damage to the device. When the V_{CC} voltage is less than 4.2 V, the base of the NPN transistor associated with the \overline{Y} is at a LOW logic state and most susceptible to an overvoltage on \overline{Y} .

Recovering primary V_{CC} power is sensed by the 3.3 V detection circuit. The PNP switching transistor is activated when the applied V_{CC} voltage reaches 3.3 V plus hysteresis. When this event occurs, the Schottky diode becomes back-biased, automatically disconnecting the lithium battery from the output and the SRAM is once again supported by the primary V_{CC} power source. Full operation is restored when the applied primary V_{CC} voltage reaches the required 4.2 V plus hysteresis value. This level is sensed by the 4.2 V detection circuit. RESET and CS are then caused to go to a HIGH logic state, and the computer memory is back in full operation without any loss of SRAM data.

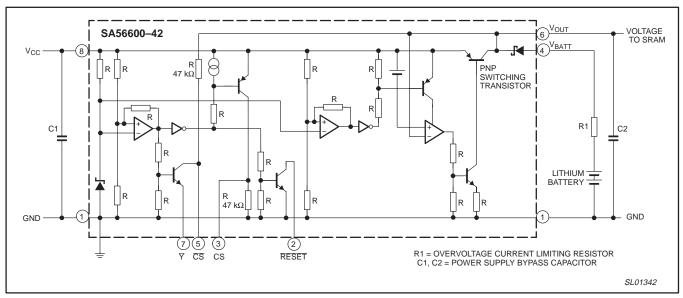


Figure 14. Functional diagram.

Product data

SA56600-42

Timing diagram

The Timing Diagram shown in Figure 15 depicts the operation of the SA56600-42 in its intended application, with a 3.0 V Lithium battery serving as a backup power source for external SRAM circuitry (see the Simplified system diagram, Figure 1). Letters indicate events along the Time axis.

A: At 'A', the V_{CC} primary power source is off. As a result of the backup battery, the \overline{CS} and V_{OUT} outputs are almost up to the Lithium battery potential (V_B). All other outputs (Y, RESET, and CS) are at or very near ground potential.

B - **C**: At 'B', the V_{CC} voltage begins to rise. Also the RESET voltage initially rises but then abruptly returns to a LOW state at 'C'. when the V_{CC} voltage reaches the level which activates the internal bias circuitry and asserts RESET to a logic LOW. This occurs at approximately 0.8 volts.

D - **E**: At 'D' the internal 3.3 V detection circuit is activated when V_{CC} voltage rises to 3.3 V. The circuit causes the PNP series pass switching transistor in the output to activate, connecting the main power supply voltage (V_{CC}) to the output. This causes the Lithium battery to be automatically disconnected from V_{OUT} by back-biasing the Schottky diode. As a result, \overline{CS} and V_{OUT} begin to rise with V_{CC}.

E: At 'E', V_{CC} has risen to the upper detection threshold (V_S plus hysteresis) as sensed by the device's internal 4.2 V detection circuit. This event signals that the output voltage is adequate to support full operation of the associated external computer circuitry. RESET goes HIGH, allowing the microprocessor circuitry to operate. Simultaneously, CS also goes HIGH, signaling the SRAM to start receiving data. \overline{CS} goes LOW as a result of \overline{Y} simultaneously being at a LOW state.

 \overline{Y} controls the \overline{CS} output. As long as \overline{Y} is LOW, the \overline{CS} output is enabled.

F: As V_{CC} continues to rise, RESET, CS, and V_{OUT} also continue to rise. Just before 'F', \overline{Y} is asserted HIGH by the microprocessing circuitry. This causes \overline{CS} to change from a LOW state to a HIGH state. Following 'F' the microprocessing circuitry is signaling \overline{Y} through repetitive cycles. This causes \overline{CS} to also cycle, but has no effect on the battery circuit.

G: At 'G', the V_{CC} voltage begins to fall. As a result $\,\overline{\text{RESET}},$ CS, and V_{CC} fall.

H: When the V_{CC} voltage falls to V_S (4.2 V) it is detected by the internal 4.2 V detector circuit. The detector circuit forces $\overrightarrow{\text{RESET}}$ and CS LOW, deselecting the SRAM and stopping data storage and retrieval. The PNP series pass switching transistor disconnects the primary input source voltage from the output, transferring the SRAM to the backup battery. In addition, because $\overrightarrow{\text{Y}}$ is already at a LOW state, $\overrightarrow{\text{CS}}$ rises abruptly close to V_S followed by a continued fall to V_B (Lithium battery potential), following V_{CC}.

J: At 'J', V_{OUT} has also fallen with V_{CC} to a level that is now dictated by the Lithium battery potential. The Lithium battery is now maintaining the V_{OUT} voltage to preserve the SRAM data.

K - L: As the V_{CC} voltage falls to a level which no longer allows the internal bias circuitry to remain active, the assertion of RESET can no longer be maintained. RESET rises slightly, then falls to ground as V_{CC} falls to ground.

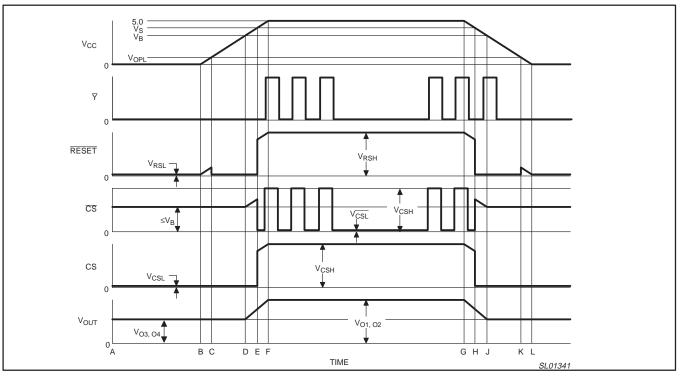


Figure 15. Timing diagram.

SA56600-42

PACKING METHOD

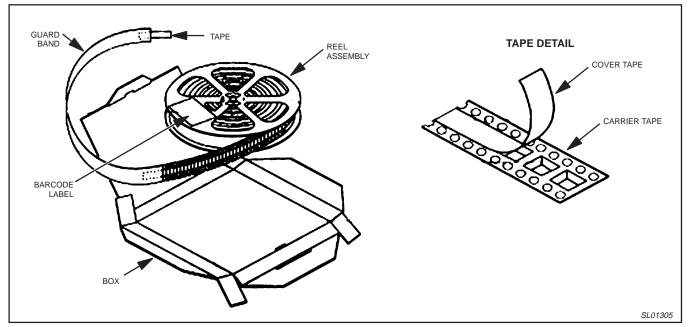
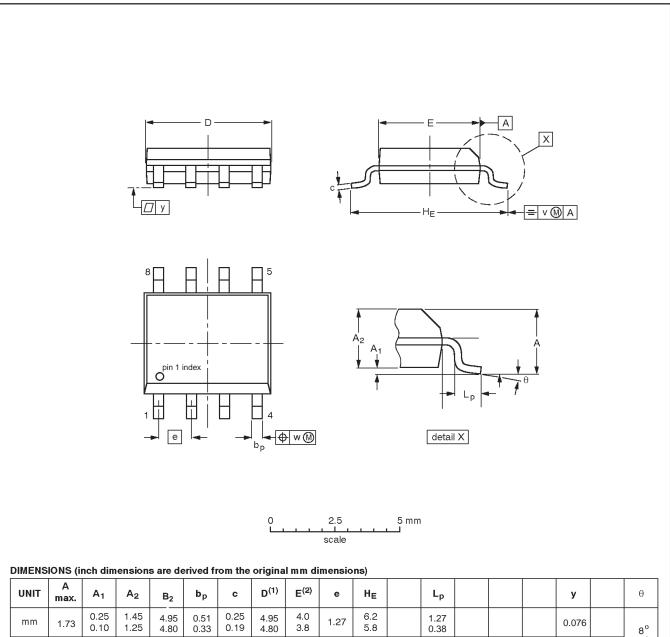


Figure 16. Tape and reel packing method.

SO8: plastic small outline package; 8 leads; body width 3.9 mm



Notes

inches

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

0.189

0.195

0.057

0.049

0.010

0.004

0.068

2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			
	IEC	JEDEC	EIAJ	
SO8	076E03	MS-012		

0.0100

0.0075

0.013

0.020

0.20

0.19

0.16

0.15

0.050

0.244

0.228

0.050

0.015

õ°

0.003

SA56600-42

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NOTES

SA56600-42

Data sheet status

Data sheet status ^[1]	Product status ^[2]	Definitions
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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